L Number	Hits	Search Text	DB	Time stamp
1	233	257/666.ccls. and laser	IICDAM.	2004/07/20
1	233	257/666.CCIS. and laser	USPAT; US-PGPUB; EPO; JPO;	2004/07/20
2	198	(257/666.ccls. and laser) and	DERWENT; IBM_TDB USPAT;	2004/07/20
		(@ad<20020128)	US-PGPUB; EPO; JPO; DERWENT; IBM TDB	12:04
3	280	257/666.ccls. and (laser or (light adjemitting))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/20
5	12	((257/666.ccls. and (laser or (light adjemitting))) and (@ad<20020128)) and (light adj receiving)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20
4	238	(257/666.ccls. and (laser or (light adjemitting))) and (@ad<20020128)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:08
6	362	257/98.ccls. and (encapsulant or encapsulate or mold or molding or epoxy) and (@ad<20020128)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20
7	359	(257/98.ccls. and (encapsulant or encapsulate or mold or molding or epoxy) and (@ad<20020128)) not ((257/666.ccls. and (laser or (light adj emitting))) and (@ad<20020128))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/20
8	221	((257/98.ccls. and (encapsulant or encapsulate or mold or molding or epoxy) and (@ad<20020128)) not ((257/666.ccls. and (laser or (light adj emitting))) and (@ad<20020128))) and (lead or leads)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/20 11:52
9	59646	<pre>(light adj (receiving or sensor)) and (laser or photodiode or (light adj (emitting or emitter)))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/20 12:03
10	59647	<pre>(light adj (receiving or sensor or receivor)) and (laser or photodiode or (light adj (emitting or emitter)))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	200.4/07/20 12:04
11	53211	((light adj (receiving or sensor or receivor)) and (laser or photodiode or (light adj (emitting or emitter)))) and (@ad<20020128)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/20 12:04
12	1813	(((light adj (receiving or sensor or receivor)) and (laser or photodiode or (light adj (emitting or emitter)))) and (@ad<20020128)) and (encapsulant or encapsulate or mold or molding or epoxy) and (lead or leads)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 12:07
13	262	257/100.ccls. and (encapsulant or encapsulate or mold or molding or epoxy) and (@ad<20020128)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TOB	2004/07/20 12:06

14	75	257/80.ccls. and (encapsulant or	USPAT;	2004/07/20
	, ,	encapsulate or mold or molding or epoxy)	US-PGPUB;	12:06
		and (@ad<20020128)	EPO; JPO;	
			DERWENT;	
			IBM TDB	
15	103		USPĀT;	2004/07/20
		encapsulate or mold or molding or epoxy)	US-PGPUB;	12:06
	,	and (@ad<20020128)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
16	0	((((light adj (receiving or sensor or	USPAT;	2004/07/20
		receivor)) and (laser or photodiode or	US-PGPUB;	12:07
		(light adj (emitting or emitter)))) and	EPO; JPO;	
		(@ad<20020128)) and (encapsulant or	DERWENT;	
	'	encapsulate or mold or molding or epoxy)	IBM_TDB	
1.7	2042	and (lead or leads)) and 385/\$.ccls	Habba	2004/07/20
17	2041	((light adj (receiving or sensor or	USPAT;	2004/07/20
		receivor)) and (laser or photodiode or (light adj (emitting or emitter)))) and	US-PGPUB;	12:07
		(light ad) (emitting or emitter))) and 385/\$.ccls.	EPO; JPO; DERWENT;	
		303/3.0018.	IBM TDB	
18	249	((((light adj (receiving or sensor or	USPAT;	2004/07/20
10	249	receivor)) and (laser or photodiode or	US-PGPUB;	12:08
		(light adj (emitting or emitter)))) and	EPO; JPO;	12.00
]		(@ad<20020128)) and (encapsulant or	DERWENT;	
		encapsulate or mold or molding or epoxy)	IBM TDB	
		and (lead or leads)) and 385/\$.ccls.	15.1_155	
19	244	(((((light adj (receiving or sensor or	USPAT;	2004/07/20
		receivor)) and (laser or photodiode or	US-PGPUB;	12:08
'		(light adj (emitting or emitter)))) and	EPO; JPO;	
!		(@ad<20020128)) and (encapsulant or	DERWENT;	
		encapsulate or mold or molding or epoxy)	IBM_TDB	
		and (lead or leads)) and 385/\$.ccls.) not	-]
		(257/98.ccls. and (encapsulant or		
		encapsulate or mold or molding or epoxy)		
	_	and (@ad<20020128))		
20	244	((((((light adj (receiving or sensor or	USPAT;	2004/07/20
		receivor)) and (laser or photodiode or	US-PGPUB;	12:08
		(light adj (emitting or emitter)))) and	EPO; JPO;	
		(@ad<20020128)) and (encapsulant or	DERWENT;	
		encapsulate or mold or molding or epoxy)	IBM_TDB	
		and (lead or leads)) and 385/\$.ccls.) not (257/98.ccls. and (encapsulant or		
		encapsulate or mold or molding or epoxy)		
		and (@ad<20020128))) and (@ad<20020128)		
L	l	and (ead\20020120)) and (ead\20020120)	l	<u> </u>